

General Purpose Transistors

NPN Silicon

MMBT3904TT1G, SMMBT3904TT1G

This transistor is designed for general purpose amplifier applications. It is housed in the SOT-416/SC-75 package which is designed for low power surface mount applications.

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V _{CEO}	40	Vdc
Collector - Base Voltage	V _{CBO}	60	Vdc
Emitter - Base Voltage	V _{EBO}	6.0	Vdc
Collector Current - Continuous	Ic	200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, FR-4 Board (Note 1) @T _A = 25°C Derated above 25°C	P _D	200 1.6	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	600	°C/W
Total Device Dissipation, FR-4 Board (Note 2) @T _A = 25°C Derated above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	400	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	-65 to +150	°C

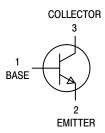
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. FR-4 @ Minimum Pad
- 2. FR-4 @ 1.0 × 1.0 Inch Pad

1

GENERAL PURPOSE AMPLIFIER TRANSISTORS SURFACE MOUNT





MARKING DIAGRAM



AM = Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT3904TT1G	SOT-416 (Pb-Free)	3,000 / Tape & Reel
SMMBT3904TT1G	SOT-416 (Pb-Free)	3,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

	Characteristic	Symbol	Min	Max	Unit
OFF CHARACTE	RISTICS			•	•
Collector – Emitter (I _C = 1.0 mAdc,	Breakdown Voltage (Note 3) I _B = 0)	V _(BR) CEO	40	-	Vdc
Collector – Base Breakdown Voltage (I _C = 10 µAdc, I _E = 0)		V _(BR) CBO	60	-	Vdc
Emitter – Base Bre (I _E = 10 μAdc, I	· · · · · · · · · · · · · · · · · · ·	V _{(BR)EBO}	6.0	-	Vdc
Base Cutoff Curre (V _{CE} = 30 Vdc,		I _{BL}	-	50	nAdc
Collector Cutoff Current (V _{CE} = 30 Vdc, V _{EB} = 3.0 Vdc)		I _{CEX}	-	50	nAdc
ON CHARACTER	RISTICS (Note 3)			1	•
$(I_C = 1.0 \text{ mAdc},$ $(I_C = 10 \text{ mAdc},$ $(I_C = 50 \text{ mAdc},$		h _{FE}	40 70 100 60 30	- 300 - -	-
		V _{CE(sat)}	<u>-</u> -	0.2 0.3	Vdc
Base – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}$, $I_B = 5.0 \text{ mAdc}$)		V _{BE(sat)}	0.65	0.85 0.95	Vdc
SMALL-SIGNAL	CHARACTERISTICS	<u> </u>		+	•
	Bandwidth Product V _{CE} = 20 Vdc, f = 100 MHz)	f _T	300	_	MHz
Output Capacitan (V _{CB} = 5.0 Vdc	ce , I _E = 0, f = 1.0 MHz)	C _{obo}	-	4.0	pF
Input Capacitance (V _{EB} = 0.5 Vdc,	e I _C = 0, f = 1.0 MHz)	C _{ibo}	-	8.0	pF
Input Impedance ($V_{CE} = 10 \text{ Vdc}, I_{C} = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz}$)		h _{ie}	1.0	10	kΩ
Voltage Feedback Ratio (V _{CE} = 10 Vdc, I _C = 1.0 mAdc, f = 1.0 kHz)		h _{re}	0.5	8.0	X 10 ⁻⁴
Small – Signal Current Gain ($V_{CE} = 10 \text{ Vdc}$, $I_C = 1.0 \text{ mAdc}$, $f = 1.0 \text{ kHz}$)		h _{fe}	100	400	-
Output Admittanc (V _{CE} = 10 Vdc,	e I _C = 1.0 mAdc, f = 1.0 kHz)	h _{oe}	1.0	40	μmhos
Noise Figure (V _{CE} = 5.0 Vdc	I_C = 100 μAdc, R_S = 1.0 k Ω , f = 1.0 kHz)	NF	-	5.0	dB
SWITCHING CHA	ARACTERISTICS				
Delay Time	(V _{CC} = 3.0 Vdc, V _{BE} = -0.5 Vdc) MMBT3904TT1G, SMMBT3904TT1G	t _d		35	
Rise Time	(I _C = 10 mAdc, I _{B1} = 1.0 mAdc) MMBT3904TT1G, SMMBT3904TT1G	t _r		35	ns
Storage Time	(V _{CC} = 3.0 Vdc, I _C = 10 mAdc) MMBT3904TT1G, SMMBT3904TT1G	t _s	-	200	
Fall Time	$(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ MMBT3904TT1G, SMMBT3904TT1G	t _f	-	50	
	•				

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

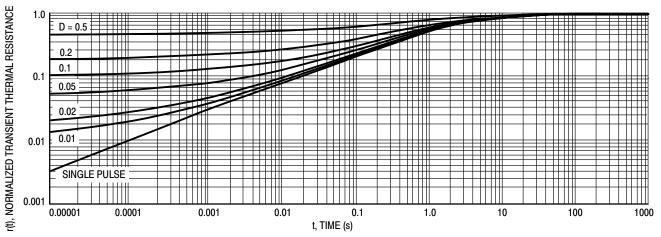
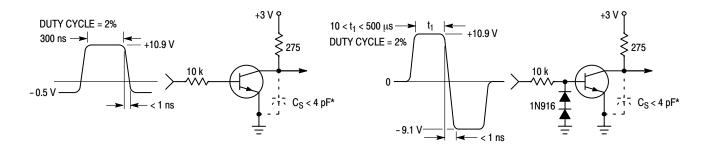


Figure 1. Normalized Thermal Response

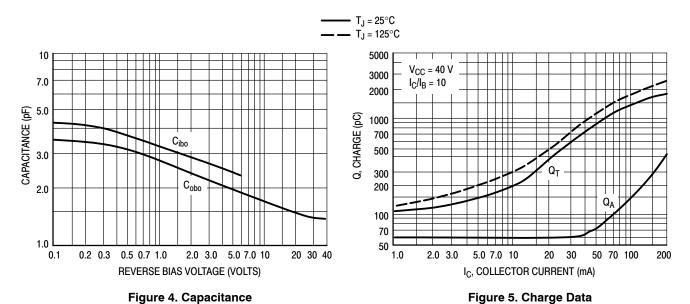


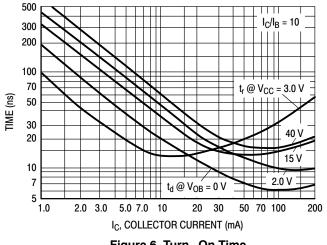
* Total shunt capacitance of test jig and connectors

Figure 2. Delay and Rise Time Equivalent Test Circuit

Figure 3. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS





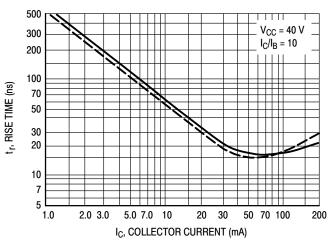
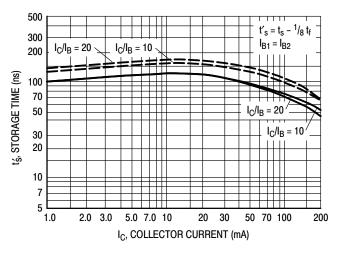


Figure 6. Turn - On Time

Figure 7. Rise Time



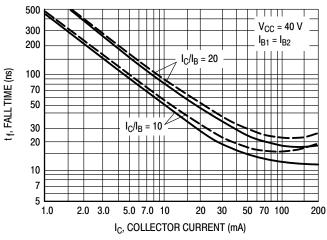
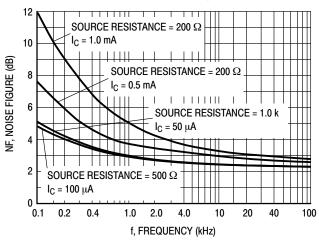


Figure 8. Storage Time

Figure 9. Fall Time

TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$



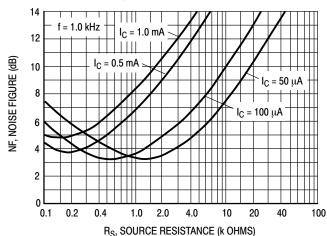
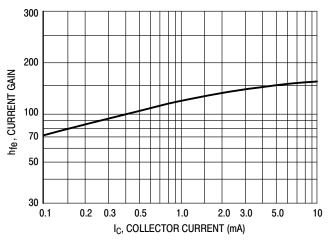


Figure 10. Noise Figure

Figure 11. Noise Figure

h PARAMETERS

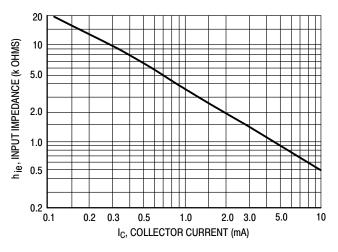
 $(V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$



100 h_{0e}, OUTPUT ADMITTANCE (μ mhos) 50 20 10 2 0.1 0.2 0.3 0.5 1.0 2.0 3.0 5.0 10 IC, COLLECTOR CURRENT (mA)

Figure 12. Current Gain

Figure 13. Output Admittance



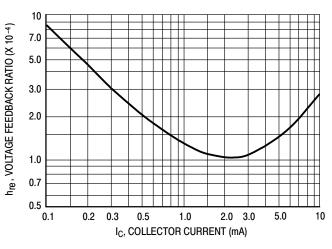


Figure 14. Input Impedance

Figure 15. Voltage Feedback Ratio

TYPICAL STATIC CHARACTERISTICS

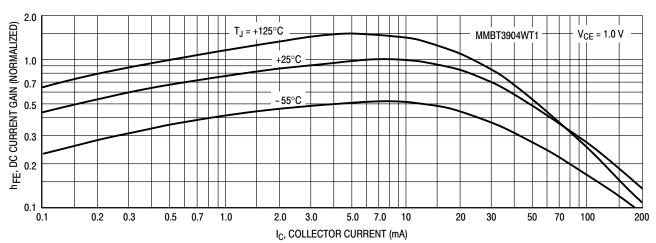


Figure 16. DC Current Gain

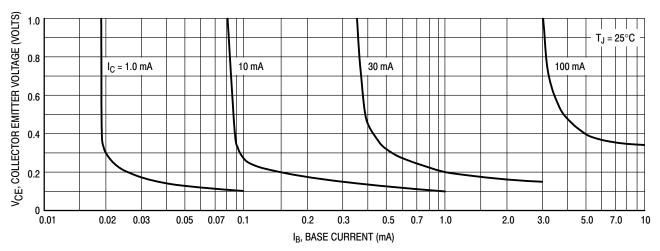


Figure 17. Collector Saturation Region

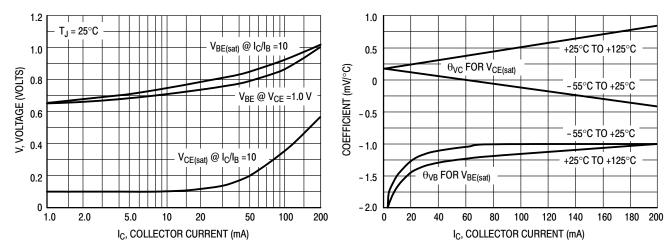


Figure 18. "ON" Voltages

Figure 19. Temperature Coefficients



SC75-3 1.60x0.80x0.80, 1.00P

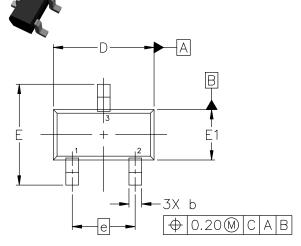
CASE 463 ISSUE H

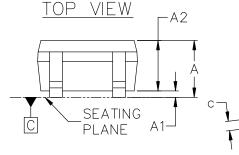
DATE 01 FEB 2024

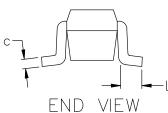


- 1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
- 2. ALL DIMENSION ARE IN MILLIMETERS.

DIM	MILLIMETERS			
	MIN.	NOM.	MAX.	
А	0.70	0.80	0.90	
A1	0.00	0.05	0.10	
A2	0.80 REF.			
b	0.15	0.20	0.30	
С	0.10	0.15	0.25	
D	1.55	1.60	1.65	
Е	1.50	1.60	1.70	
E1	0.70	0.80	0.90	
е	1.00 BSC			
L	0.10	0.15	0.20	







SIDE VIEW

GENERIC MARKING DIAGRAM*



XX = Specific Device Code

M = Date Code

= Pb-Free Package

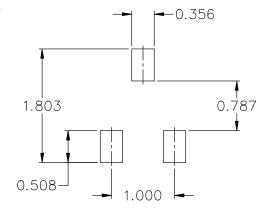
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:	
PIN 1. BASE	
O ENGITTED	

1. BASE 2. EMITTER 3. COLLECTOR STYLE 2: PIN 1. ANODE 2. N/C 3. CATHODE STYLE 3: PIN 1. ANODE 2. ANODE 3. CATHODE FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES

REFERENCE MANUAL, SOLDERRM/D.

RECOMMENDED MOUNTING FOOTPRINT*



 STYLE 4:
 STYLE 5:

 PIN 1. CATHODE
 PIN 1. GATE

 2. CATHODE
 2. SOURCE

 3. ANODE
 3. DRAIN

DOCUMENT NUMBER:

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DESCRIPTION: SC75-3 1.60x0.80x0.80, 1.00P

98ASB15184C

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